

Description

The DFH10AL12EZC1 is a 3-level Power Module. It integrates 1200V SiC MOSFET chips and 1200V IGBT chips designed for the applications such as Solar Inverter, High frequency switching, Energy storage Systems etc.



Features

- Blocking voltage:1200V
- $R_{ds(on)}$: 9.5m Ω ($V_{GS}=15V$)/8.3m Ω ($V_{GS}=18V$)
- Low Switching Losses
- High current density
- Press FIT Contact Technology
- 175°C maximum junction temperature
- Thermistor inside

Applications

- Solar inverter Systems
- Three-level applications
- Energy Storage Systems
- High Frequency Switching application

Circuit diagram

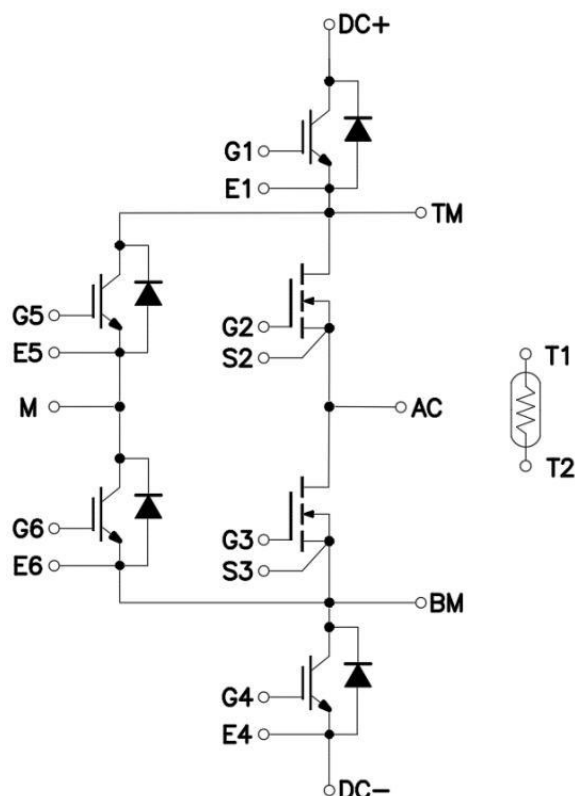


Figure 1. Out drawing & circuit diagram for DFH10AL12EZC1

Pin Configuration

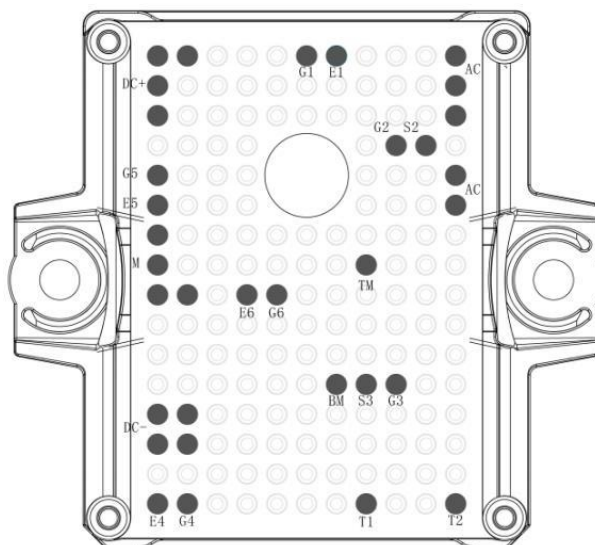


Figure 2. Pin configuration

Module

Parameter	Conditions	Value	Unit
Isolation voltage	Main terminal to base plate, RMS, f =50Hz, t =1min	3.0	kV
Creepage distance	terminal to heatsink	11.5	mm
	terminal to terminal	6.3	
Clearance	terminal to heatsink	10.0	mm
	terminal to terminal	5.0	
Comparative tracking index	-	> 400	
Mounting torque for module mounting	Screw M4 baseplate to heatsink	1.8 to 2.2	Nm
Storage temperature	-	-40 to 125	°C
Weight	-	40	g

NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
R ₂₅	Resistance	T _c = 25°C	-	5	-	kΩ
ΔR/R	Deviation of R ₁₀₀	T _c = 100°C, R ₁₀₀ = 493Ω	-5	-	5	%
P ₂₅	Power dissipation	T _c = 25°C	-	-	20	mW
B _{25/50}	B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3375	-	K
B _{25/80}	B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3411	-	K
B _{25/100}	B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3433	-	K

Maximum Ratings (SiC MOSFET , $T_j=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{DS}	Drain-Source Voltage	G-S Short	1200	V
V_{GS}	G-S Voltage	D-S Short, Note1	-10 to 22	V
I_{DS}	DC Continuous Drain Current	$T_C=125^{\circ}\text{C}$	100	A
I_{SD}	Source (Body diode) Current	$T_C=125^{\circ}\text{C}$	32	A
I_{DP}	Drain Pulse Current, Peak	Less than 1ms, Note2	200	A
T_j	junction temperature	-	-40 to 175	$^{\circ}\text{C}$

Note1: Recommended Operating Value, +18V/-5V, +15V/-4V, +15V/-5V

Note2: Pulse width limited by maximum junction temperature

Maximum Ratings (IGBT and FRD , $T_j=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{CES}	Collector-Emitter Voltage	G-E Short	1200	V
V_{GES}	Gate-Emitter Voltage	C-E Short	± 20	V
I_{CN}	DC Continuous Collector Current	$T_C=135^{\circ}\text{C}$	100	A
I_{CM}	Pulse Collector Current	$t_p=1\text{ms}$, Note1	200	A
I_F	Diode forward Current	$T_C=100^{\circ}\text{C}$	100	A
I_{FRM}	Repetitive peak forward Current	$t_p=1\text{ms}$, Note1	200	A
T_j	junction temperature	-	-40 to 175	$^{\circ}\text{C}$
T_{stg}	Storage temperature	-	-40 to 125	$^{\circ}\text{C}$

Note1: Pulse width limited by maximum junction temperature

MOSFET Electrical characteristics ($T_j=25^{\circ}\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit
			Min.	Typ.	Max	

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=200\mu A$		1200	-	-	V
I_{DSS}	Zero gate voltage drain Current	$V_{DS}=1200V, V_{GS}=0V$		-	2	-	μA
$V_{GS(th)}$	Gate-source threshold Voltage	$I_D=70mA, V_{DS}=V_{GS}, T_j=25^\circ C$		1.8	2.7	-	V
		$I_D=70mA, V_{DS}=V_{GS}, T_j=175^\circ C$		-	2.05	-	V
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=20V, V_{DS}=0V, T_j=25^\circ C$		-	200	-	nA
$R_{DS(on)}$ (Chip)	Static drain-source On-state resistance	$I_D=100A$ $V_{GS}=15V$	$T_j=25^\circ C$	-	9.5	-	m Ω
			$T_j=175^\circ C$	-	14.3	-	m Ω
		$I_D=100A$ $V_{GS}=+18V$	$T_j=25^\circ C$	-	8.3	12.5	m Ω
			$T_j=175^\circ C$	-	12.6	-	m Ω
$V_{DS(on)}$ (Chip)	Static drain-source On-state Voltage	$I_D=100A$ $V_{GS}=15V$	$T_j=25^\circ C$	-	0.95	-	V
			$T_j=175^\circ C$	-	1.43	-	V
		$I_D=100A$ $V_{GS}=+18V$	$T_j=25^\circ C$	-	0.83	1.25	V
			$T_j=175^\circ C$	-	1.26	-	V
C_{iss}	Input Capacitance	$V_D=800V, V_{GS}=0V$ $f=1MHz, V_{AC}=25mV$		-	11.6	-	nF
C_{oss}	Output Capacitance			-	0.352	-	nF
C_{rss}	Reverse transfer Capacitance			-	0.028	-	nF

Q _G	Total gate charge	V _{DD} =800V, I _D =120A, V _{GS} =-5/+15V		-	360	-	nC
R _{Gint}	Internal Gate Resistance	f=1Mhz, V _{AC} =25mV		-	0.65	-	Ω
t _{d(on)}	Turn-on delay time	V _{DD} =600V I _D =100A V _{GS} =+15V/-4V R _g =5.1Ω Inductive load switching operation	T _j =25°C	-	43	-	ns
			T _j =150°C	-	40	-	
t _r	Rise time		T _j =25°C	-	23	-	ns
			T _j =150°C	-	19	-	
t _{d(off)}	Turn-off delay time		T _j =25°C	-	112	-	ns
			T _j =150°C	-	120	-	
t _f	Fall time		T _j =25°C	-	15	-	ns
			T _j =150°C	-	40	-	
E _{on}	Turn-on power dissipation		T _j =25°C	-	2.22	-	mJ
			T _j =150°C	-	2.31	-	
E _{off}	Turn-off power dissipation		T _j =25°C	-	1.50	-	mJ
			T _j =150°C	-	1.59	-	
R _{th(j-c)}	FET Thermal Resistance	Junction to Case/MOSFET		-	0.32	-	K/W
R _{th(c-s)}	Thermal Resistance, Case to sink (Conductive Grease applied) , Note1			-	0.12	-	K/W

Note1: Assumes Thermal Conductivity of grease is 2.8W/m·K and thickness is 50um.

Body Diode Electrical characteristics (T_j=25°C unless otherwise specified, chip: Target)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{SD}	Body Diode Forward Voltage	V _{GS} =-5V I _{SD} =100A	T _j =25°C	-	5.1	-	V
			T _j =175°C	-	4.6	-	
T _{rr}	Reverse recovery time	V _{DD} =600V I _D =100A V _{GS} =+15/-4V	T _j =25°C	-	26	-	ns
			T _j =150°C	-	50	-	
Q _{rr}	Reverse recovery charge	R _g =5.1Ω Inductive load switching operation	T _j =25°C	-	0.75	-	μC
			T _j =150°C	-	3.20	-	
E _{rr}	Diode switching power		T _j =25°C	-	0.12	-	mJ

	dissipation		$T_j=150^{\circ}\text{C}$	-	0.79	-	
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IGBT Electrical characteristics ($T_j=25^{\circ}\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
$V_{CE(sat)}$ (Chip)	Collector-Emitter Saturation Voltage	$I_C=100\text{A}$ $V_{GE}=15\text{V}$	$T_j=25^{\circ}\text{C}$	-	1.56	-	V
			$T_j=175^{\circ}\text{C}$	-	1.81	-	V
$V_{GE(th)}$	Gate-Emitter threshold Voltage	$I_C=2.6\text{mA}$, $V_{CE}=10\text{V}$		-	5.9	-	V
Q_G	Gate charge	$V_{GE}=-15\text{V}$ to $+15\text{V}$		-	2.0	-	μC
R_{Gint}	Internal gate resistor	-	$T_j=25^{\circ}\text{C}$	-	13	-	Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$ $f=1\text{MHz}$	$T_j=25^{\circ}\text{C}$	-	3.56	-	nF
C_{res}	Reverse transfer Capacitance			-	0.04	-	nF
I_{CES}	Collector- Emitter Cut off Current	$V_{CE}=1200\text{V}$, $V_{GE}=0\text{V}$	$T_j=25^{\circ}\text{C}$	-	-	0.01	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=20\text{V}$, $V_{CE}=0\text{V}$	$T_j=25^{\circ}\text{C}$	-	-	0.1	μA

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td(on)	Turn-on delay time	V _{CC} =600V I _C = 100A V _{GE} =+15V/-15V R _g =1.5Ω Inductive load	T _j =25°C	-	100	-	ns
			T _j =125°C	-	108	-	
			T _j =175°C	-	114	-	
tr	Rise time		T _j =25°C	-	31	-	ns
			T _j =125°C	-	34	-	
			T _j =175°C	-	37	-	
td(off)	Turn-off delay time		T _j =25°C	-	228	-	ns
			T _j =125°C	-	299	-	
			T _j =175°C	-	342	-	
tf	Fall time		T _j =25°C	-	210	-	ns
			T _j =125°C	-	308	-	
			T _j =175°C	-	384	-	
E _{on}	Turn-on power dissipation		T _j =25°C	-	1.24	-	mJ
			T _j =125°C	-	1.80	-	
			T _j =175°C	-	2.01	-	
E _{off}	Turn-off power dissipation	T _j =25°C	-	6.7	-	mJ	
		T _j =125°C	-	12.2	-		
		T _j =175°C	-	15.1	-		
R _{th(j-c)}	Thermal Resistance, Junction to Case (IGBT)			-	0.16	-	K/W
R _{th(c-s)}	Thermal Resistance, Case to sink (Conductive Grease applied) , Note1			-	0.12	-	K/W

Note1: Assumes Thermal Conductivity of grease is 2.8W/m·K and thickness is 50um.

Freewheeling Diode Electrical characteristics (T_j =25°C unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _F	Diode Forward Voltage	I _F =100A, V _{GE} =0V	T _J =25°C	-	1.9	-	V
			T _J =175°C	-	1.75	-	
			T _J =25°C	-	0.36	-	

t_{rr}	Reverse recovery time	(Switch side) $V_{CC}=600V$ $I_C=100A$ $V_{GE}=+15V/-15V$ $R_g=1.5\Omega$ (FRD side) $V_{rr}=600V$ $I_F=100A$ $V_{GE}=+15V/-15V$ Inductive load switching operation	$T_j=125^{\circ}C$	-	0.53	-	us	
			$T_j=175^{\circ}C$	-	0.71	-		
I_{RM}	Peak reverse recovery Current		$T_j=25^{\circ}C$	-	103	-	A	
			$T_j=125^{\circ}C$	-	131	-		
			$T_j=175^{\circ}C$	-	154	-		
Q_{rr}	Recovered charge		$T_j=25^{\circ}C$	-	9.32	-	uC	
			$T_j=125^{\circ}C$	-	16.7	-		
			$T_j=175^{\circ}C$	-	27.2	-		
E_{rr}	Reverse recovered energy		$T_j=25^{\circ}C$	-	3.74	-	mJ	
			$T_j=125^{\circ}C$	-	6.90	-		
			$T_j=175^{\circ}C$	-	8.77	-		
$R_{th(j-c)}$	Thermal Resistance, Junction to Case (Diode)			-	0.28	-	K/W	
$R_{th(c-s)}$	Thermal Resistance, Case to sink (Conductive Grease applied) , Note1			-	0.12	-	K/W	

Note1: Assumes Thermal Conductivity of grease is $2.8W/m \cdot K$ and thickness is $50\mu m$.

Test Conditions

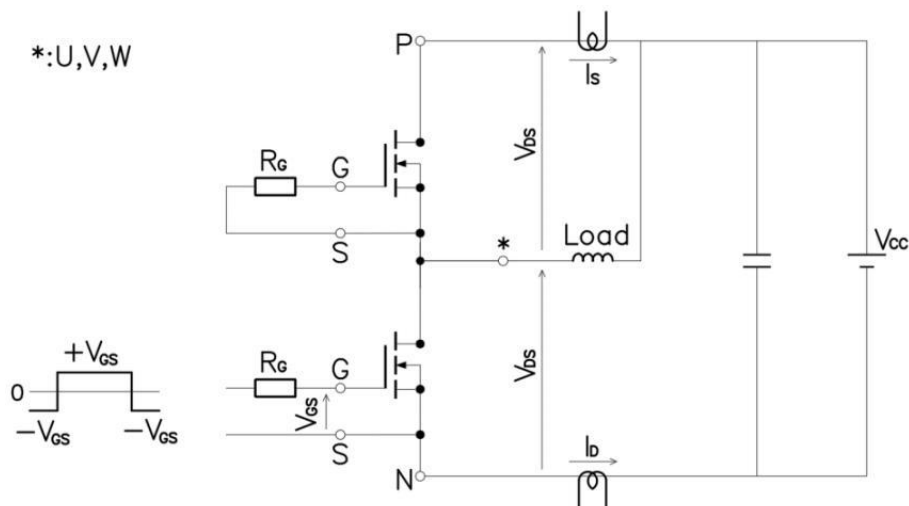


Figure 3. Switching time measure circuit

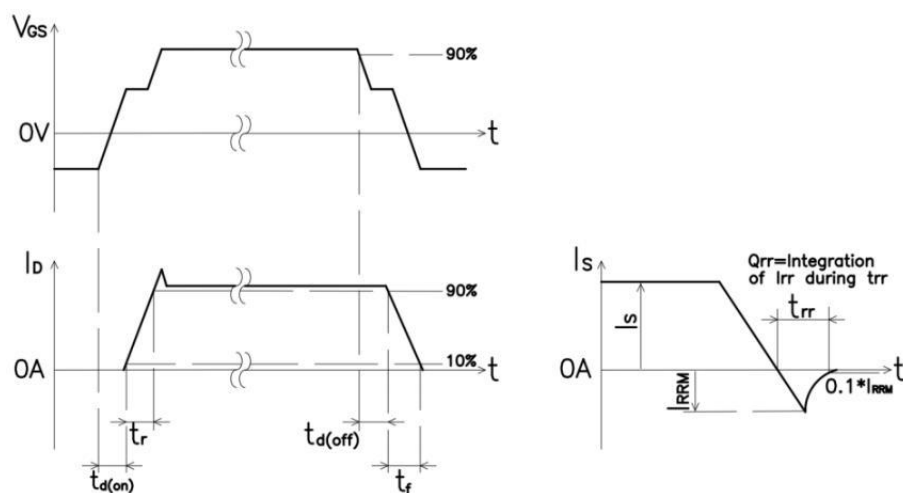


Figure 4. Switching time definition

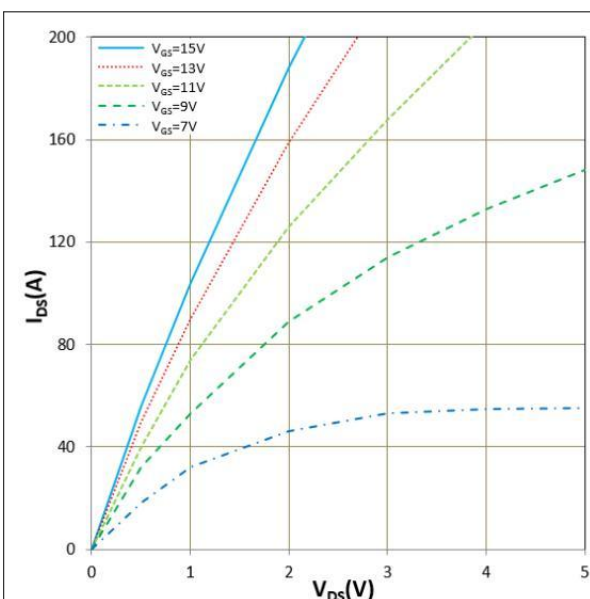


Figure 5. I_{DS} vs V_{DS} , SiC MOSFET
 $T_j = 25^\circ\text{C}$, V_{GS} parameter

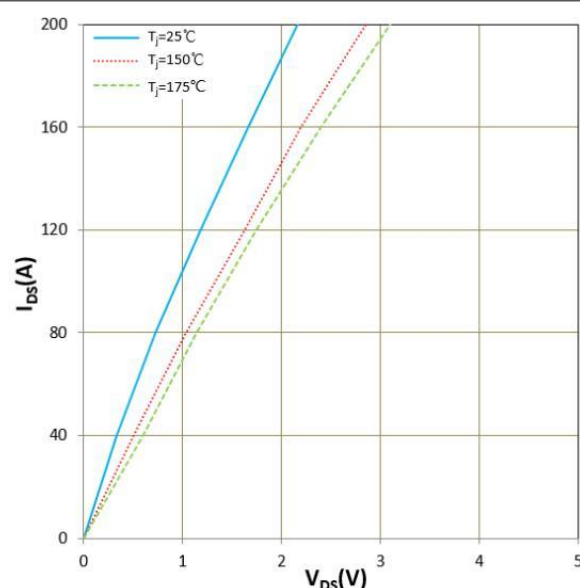


Figure 6. I_{DS} vs V_{DS} , SiC MOSFET
 $V_{GS} = +15\text{V}$

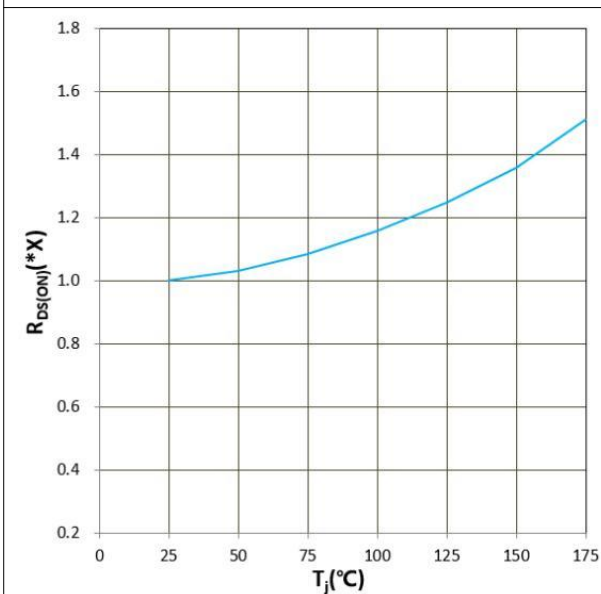


Figure 7. $R_{DS(ON)}$ vs T_j , SiC MOSFET
 $V_{GS} = +15\text{V}$, $I_D = 100\text{A}$, $1.0X = 9.5\text{m}\Omega$

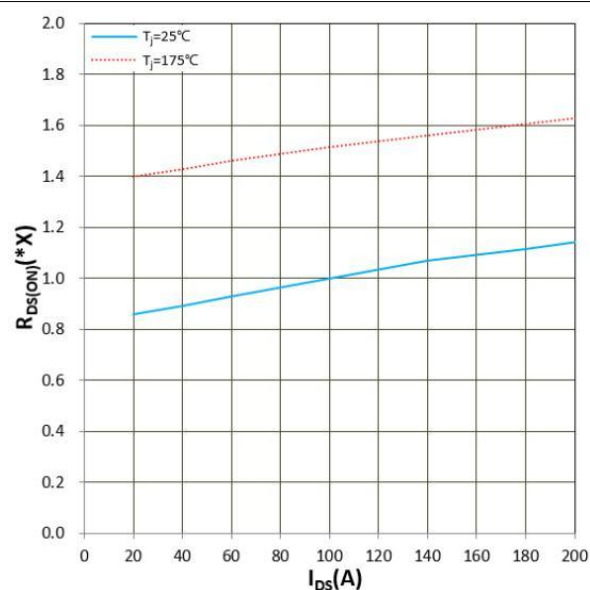


Figure 8. $R_{DS(ON)}$ vs I_{DS} , SiC MOSFET
 $V_{GS} = +15\text{V}$, $1.0X = 9.5\text{m}\Omega$

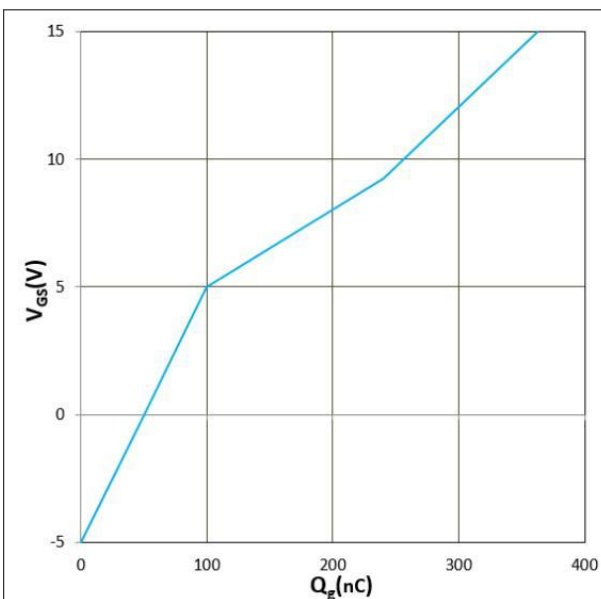


Figure 9. V_{GS} vs Q_g , SiC MOSFET
 $V_{DS}=800V$, $I_D=120A$, $T_j=25^\circ C$

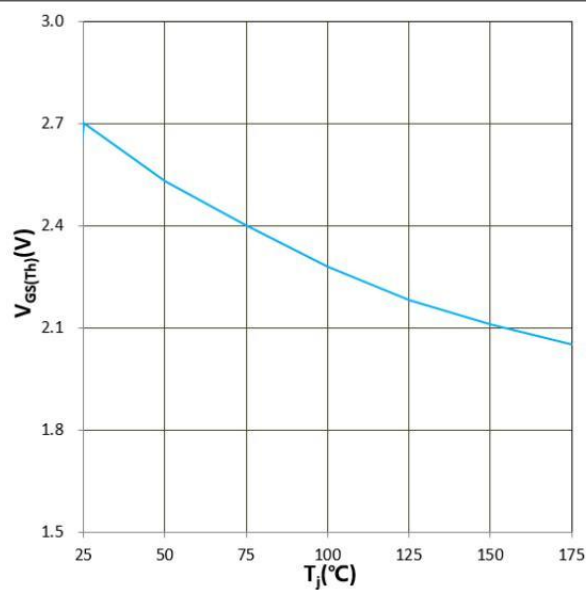


Figure 10. $V_{GS(TH)}$ vs T_j , SiC MOSFET
 $V_{GS}=V_{DS}$, $I_D=70mA$

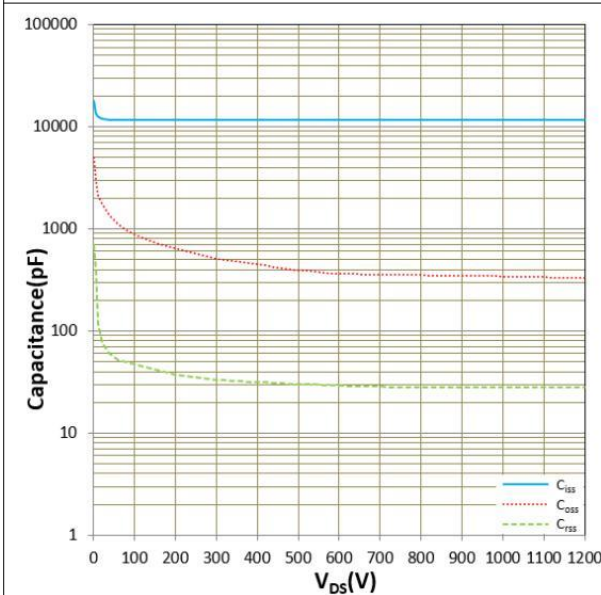


Figure 11. C_{iss} , C_{oss} , C_{rss} vs V_{DS} , SiC MOSFET
 $T_j=25^\circ C$, $V_{GS}=0V$, $f=1MHz$

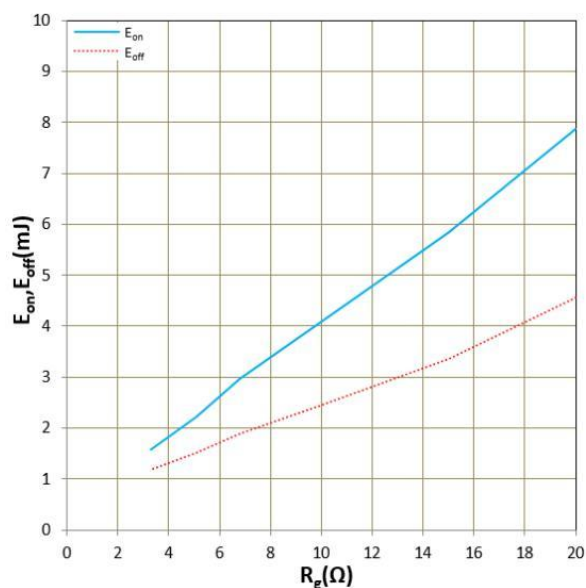


Figure 12. E_{on} , E_{off} vs R_g , SiC MOSFET
 $T_j=25^\circ C$, $V_{CC}=600V$, $I_D=100A$, $V_{GS}=+15V/-4V$

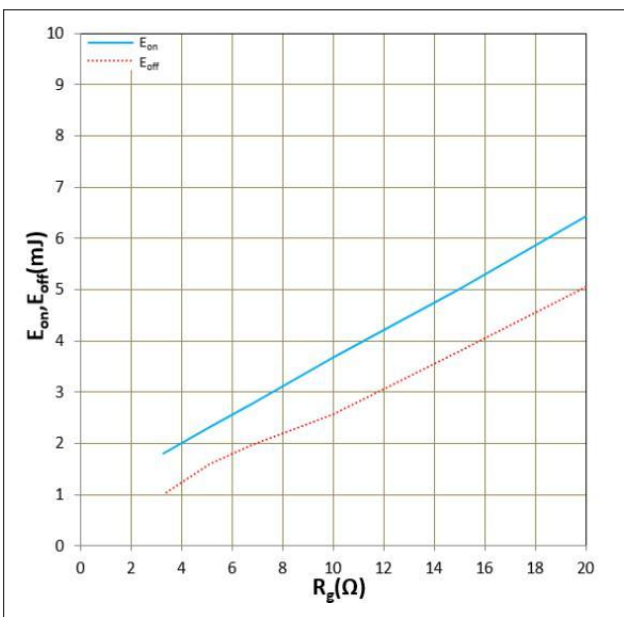


Figure 13. E_{on} , E_{off} vs R_g , SiC MOSFET
 $T_j = 150^\circ\text{C}$, $V_{CC} = 600\text{V}$, $I_D = 100\text{A}$, $V_{GS} = +15\text{V}/-4\text{V}$

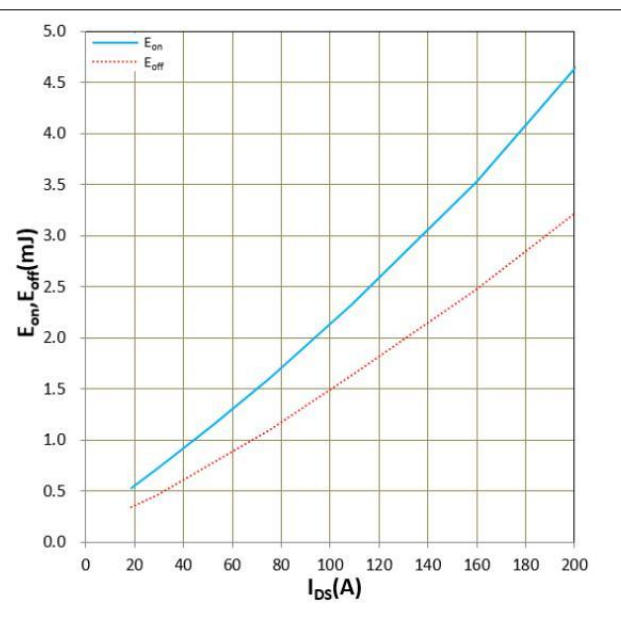


Figure 14. E_{on} , E_{off} vs I_{DS} , SiC MOSFET
 $T_j = 25^\circ\text{C}$, $V_{CC} = 600\text{V}$, $R_g = 5.1\Omega$, $V_{GS} = +15\text{V}/-4\text{V}$

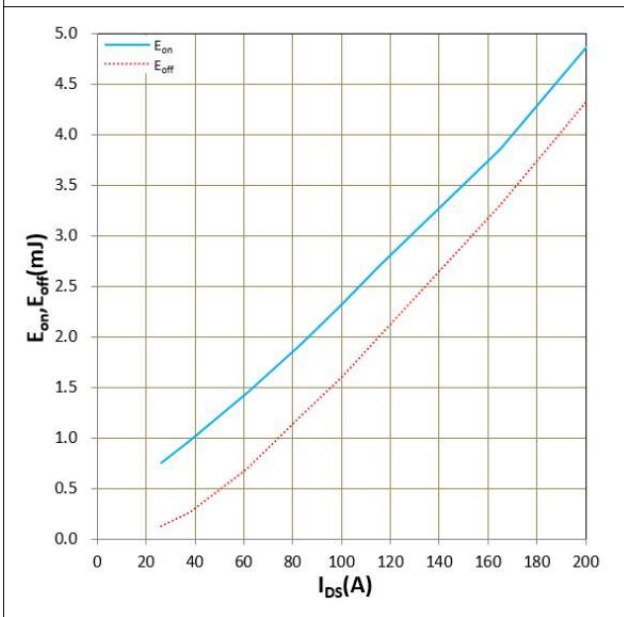


Figure 15. E_{on} , E_{off} vs I_{DS} , SiC MOSFET
 $T_j = 150^\circ\text{C}$, $V_{CC} = 600\text{V}$, $R_g = 5.1\Omega$, $V_{GS} = +15\text{V}/-4\text{V}$

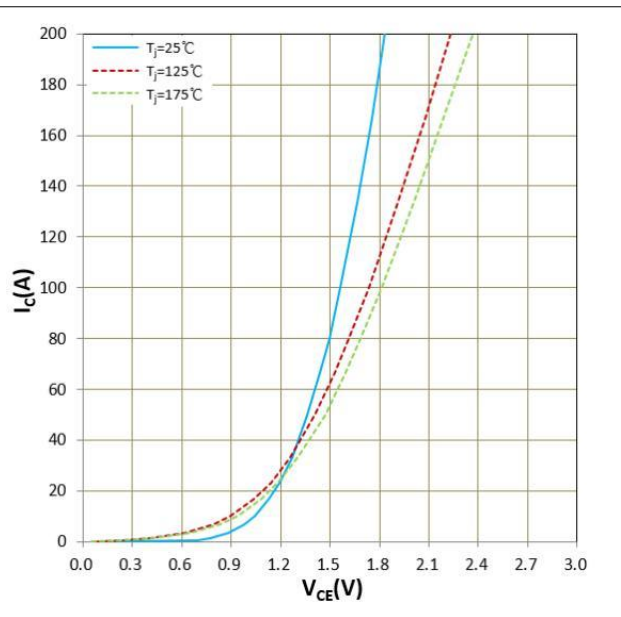


Figure 16. I_c vs V_{GE} , IGBT
 $V_{GE} = 15\text{V}$

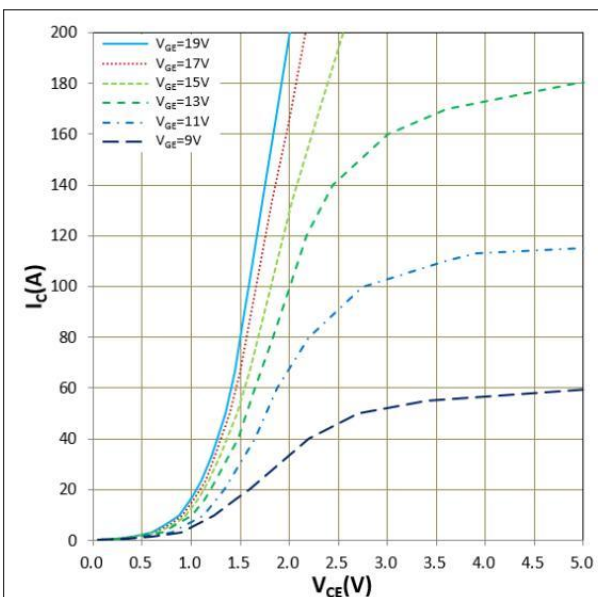


Figure 17. I_c vs V_{ce} , IGBT
 $T_j = 175^\circ\text{C}$

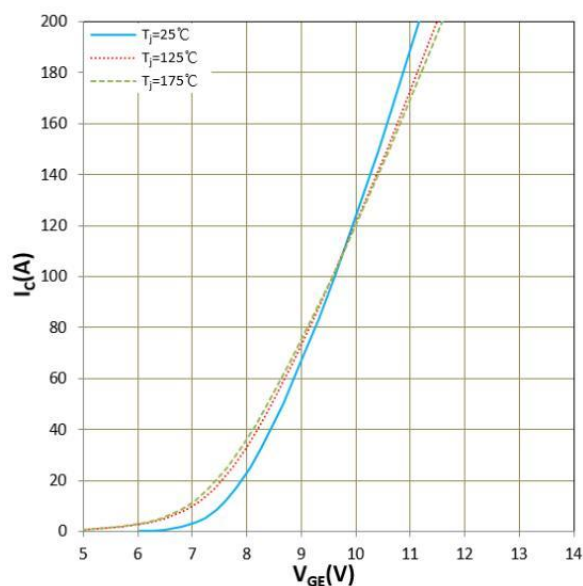


Figure 18. I_c vs V_{ge} , IGBT
 $V_{ce} = 20\text{V}$

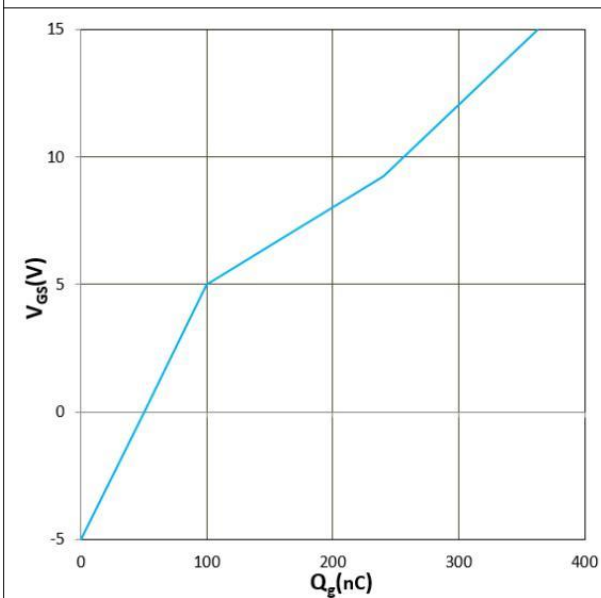


Figure 19. V_{ge} vs Q_g , IGBT
 $V_{cc} = 600\text{V}$, $I_D = 100\text{A}$, $T_j = 25^\circ\text{C}$

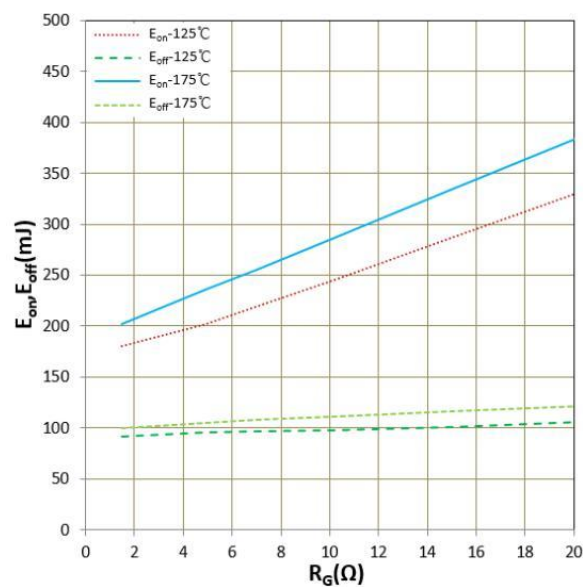


Figure 20. E_{on} , E_{off} vs I_c , IGBT
 $V_{cc} = 600\text{V}$, $V_{ge} = \pm 15\text{V}$, $R_g = 1.5\Omega$

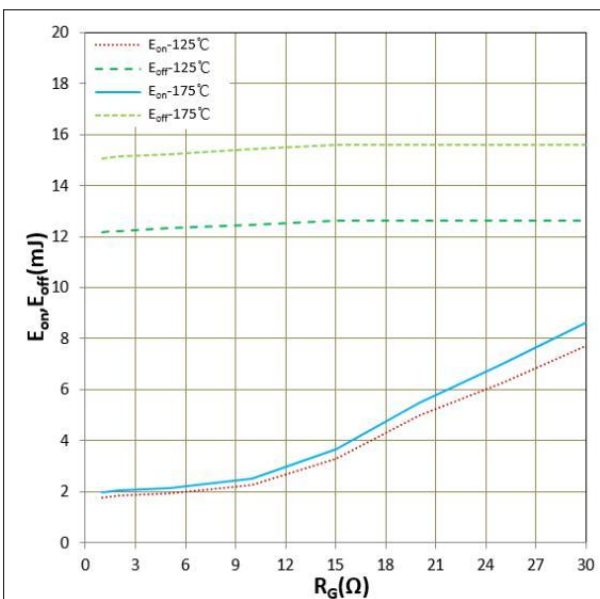


Figure 21. E_{on} , E_{off} vs R_g , IGBT
 $V_{CC}=600V$, $V_{GE}=\pm 15V$, $I_C=100A$

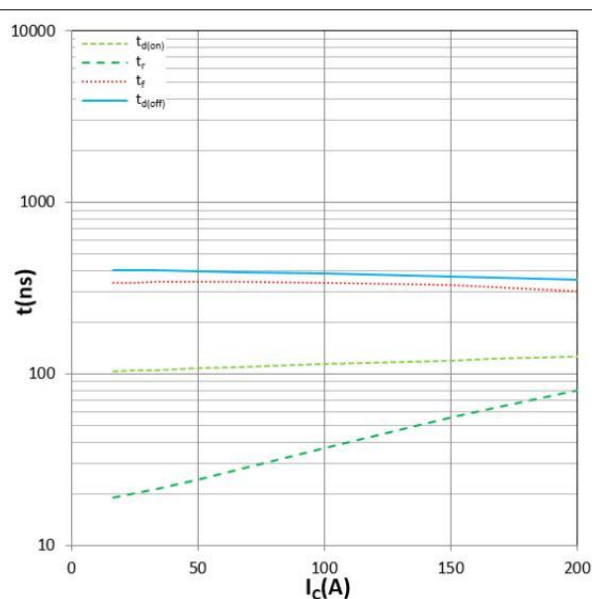


Figure 22. Switching time vs I_C , IGBT
 $V_{CC}=600V$, $V_{GE}=\pm 15V$, $R_g=1.5\Omega$, $T_j=175^\circ C$

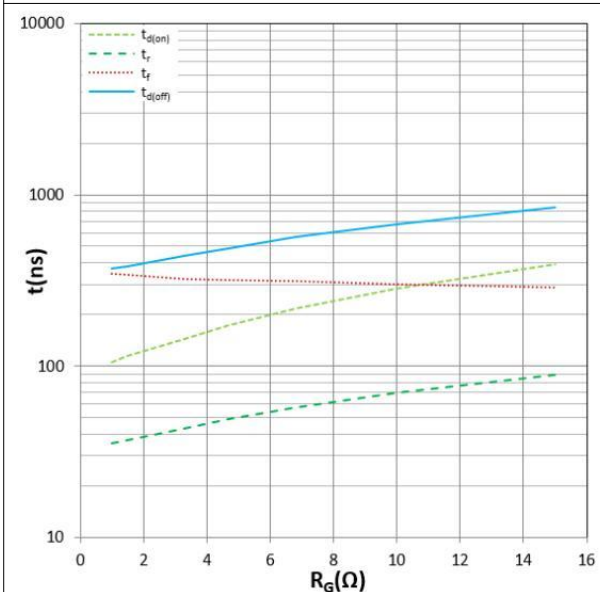


Figure 23. Switching time vs R_g , IGBT
 $V_{CC}=600V$, $V_{GE}=\pm 15V$, $I_C=100A$, $T_j=175^\circ C$

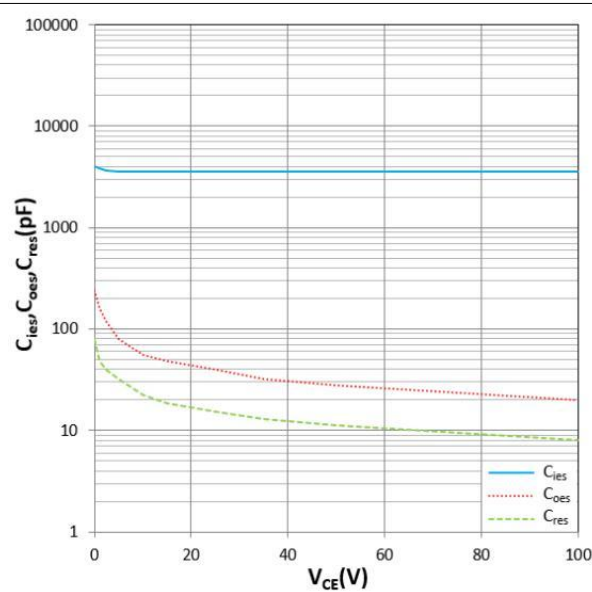


Figure 24. C_{ies} , C_{oss} , C_{res} vs V_{CE} , IGBT
 $T_j=25^\circ C$, $V_{GE}=0V$, $f=1MHz$

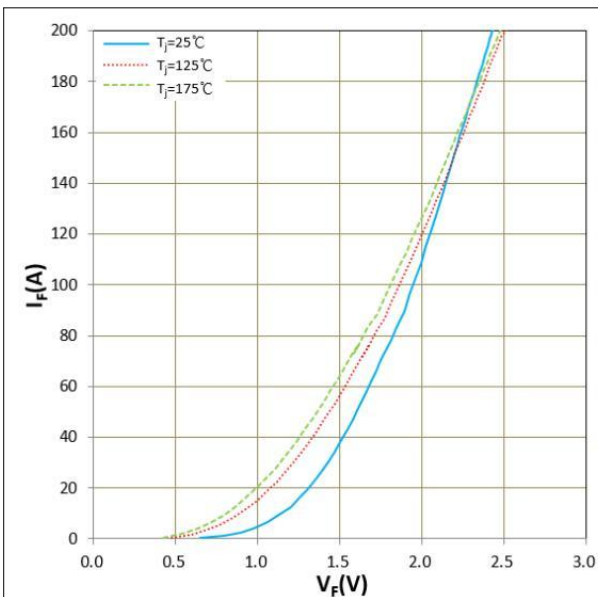


Figure 25. I_F vs V_F , Freewheeling Diode

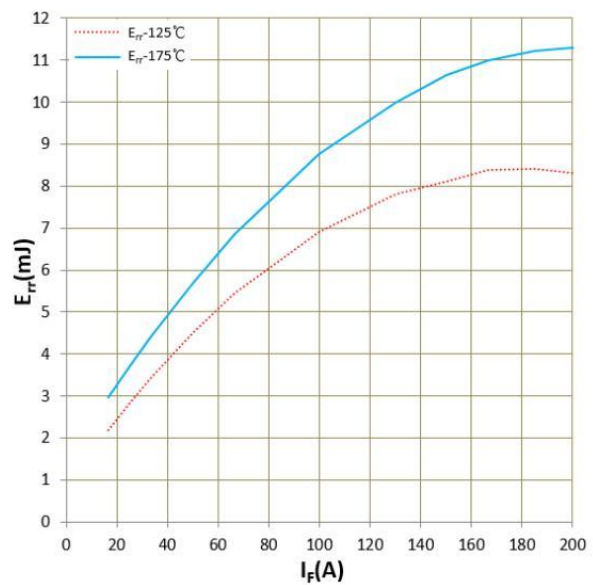


Figure 26. E_{rr} vs I_F , Freewheeling Diode
 $V_{CC}=600V$, $R_g=1.5\Omega$

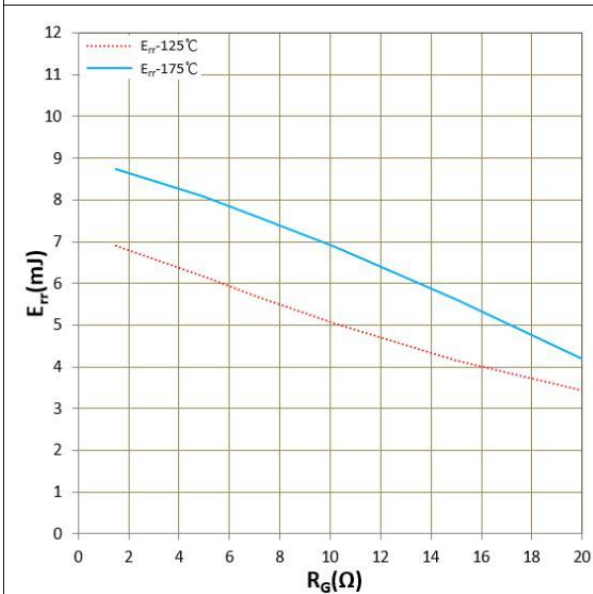
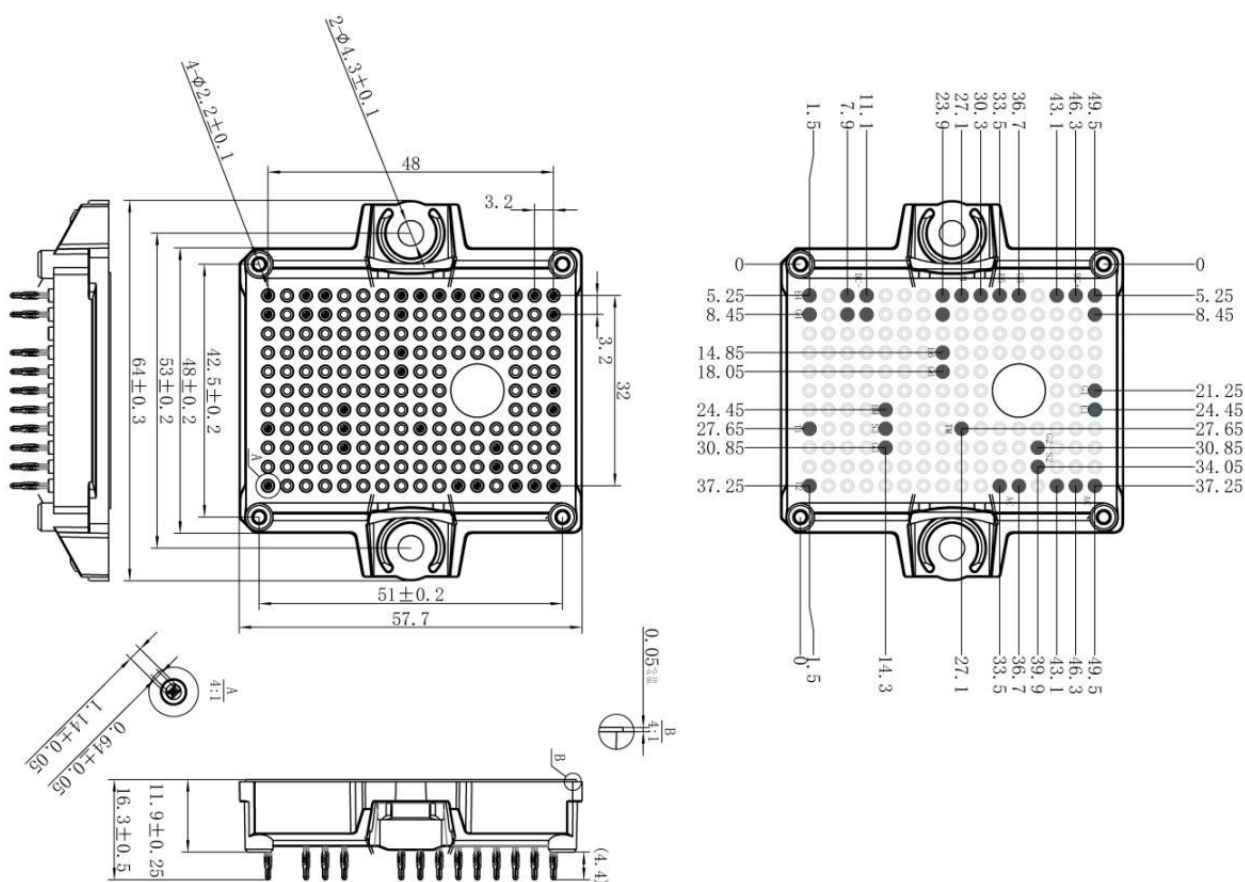


Figure 27. E_{rr} vs R_g , Freewheeling Diode
 $V_{CC}=600V$, $I_C=100A$

Package dimensions



IMPORTANT NOTICE

This product data sheet describes the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively under the terms and conditions of the supply agreement. There will be no guarantee or of any kind for the product and its characteristics.

The data contained in this document is exclusively intended for technically trained staff. You and your technical departments will have to evaluate the product's suitability for the intended application and the completeness of the product data concerning such application.

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